International Rectifier

IRFK3D250,IRFK3F250

Isolated Base Power HEX-pakTM Assembly - Half Bridge Configuration

- · High Current Capability.
- UL recognised E78996.
- · Electrically Isolated Base Plate.
- · Easy Assembly into Equipment.

Description

The HEX-pakTM utilises the well-proven HEXFETTM die, combining low on-state resistance with high transconductance. These superior technology die are assembled by state of the art techniques into the TO-240 package, featuring 2.5kV rms isolation and solid M5 screw connections. The small footprint means the package is highly suited to power applications where space is a premium. Available in two versions, IRFK.D... for fast switching and IRFK.F... for oscillation sensitive applications.

V _{DS} = 200V
$R_{DS(on)} = 30m\Omega$
I _D = 70A

Absolute Maximum Rating

	Parameter	Max.	Units
I _D @ T _C =25°C	Continuous Drain Current	70	Α
I _D @ T _C =100°C	Continuous Drain Current	41	А
I _{DM}	Pulse Drain Current	280	A ①
P _D @ T _C =25°C	Maximum Power Dissipation	625	w
V _{GS}	Gate-to-Source Voltage	20	V
V _{INS}	R.M.S. Isolation Voltage, circuit to base	2.5	· kV
Т	Operating Junction Temperature Range	-40 to 150	°C
T _{STG}	Storage Temperature Range	-40 to 150	°C

Thermal and Mechanical Specifications

	Parameter	Min.	Тур.	Max.	Units
R _{thJC}	Junction-to-Case	-	-	0.20	K/W ②
R _{thCS}	Case-to-Siлk, smooth & greased surface	-	-0.1		K/W
Т	Mounting Torque +10%				3
	HEXpak to Heatsink	-	5	-	Nm
	Busbar to HEXpak	-	3	-	l Nm
wt	Approximate Weight	-	140	-	g
		_	5	- ,	· oz

Notes:

- ① Repetitive Rating: Pulse width limited by maximum junction temperature see figure 8.
- 2 Per Module.
- ③ A mounting compound is recommended and the torque should be rechecked after a period of three hours to allow for the spread of the compound.

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Electrical Characteristics @ T_J = 25°C (Unless otherwise specified)

	Parameter		Min.	Тур.	Max.	Units	Test Conditions
B _{VDSS}	Drain-to-Source Breakd	own	200	-		V	V _{GS} =0V, I _D =1.0mA
R _{DS(on)}	Static Drain-to-Source		-	24	30	mΩ	V _{GS} =10V, I _D =41A
(,	On-State Resistance						-
I _{D(on)}	On-State Drain Current		70	-	-	Α	$V_{DS} > I_{D(on)} \times R_{DS(on)} max,$ $V_{GS} = 10V$
V _{GS(th)}	Gate Threshold Voltage		2.0		4.0	V	V _{DS} =V _{GS} , I _D =1.0mA
g _{fs}	Forward Transconductance		36	54	-	S	V _{DS} > 50V, I _D =41A
I _{DSS}	Zero Gate Voltage Drain	Current	-	-	0.75	mĀ	V _{DS} =V _{DS} max, V _{GS} =0v
			-	-	3.0	mA	V _{GS} =10V, T _C =125°C,
							V _{DS} =V _{DS} max x 0.8
I _{GSS}	Gate-to-Source Leakage Forward		-	-	300	nΑ	V _{GS} =20V
I _{GSS}	Gate-to-Source Leakage Reverse		-	-	-300	nA	V _{GS} =-20V
Qg	Total Gate Charge		-	260	390	nC	I _D =70A, V _{GS} =10V,
Q _{gs}	Gate-to-Source Charge		-	48	72	nC	V _{DS} =V _{DS} max x 0.8
Q _{gd}	Gate-to-Drain ("Miller") Charge		-	138	210	пC	
t _{d(on)}	Turn-on Delay Time	IRFK3D250	-	40	-	ns	V _{DD} =95V, I _D =41A,
		IRFK3F250	-	45	-	ns	
t _r	Rise Time	IRFK3D250	-	100	-	ns	V _{GS} =10V,
	<u> </u>	IRFK3F250	<u> </u>	125_	-	ns	
$t_{d(off)}$	Turn-off Delay Time	IRFK3D250	-	160	-	กร	$R_{SOURCE}=3.3\Omega$
		IRFK3F250	<u>-</u>	210	-	пѕ	
t _f	Fall Time	IRFK3D250		50	-	ns	
	IRFK3F250		.	80	-	ns	
L _{DS}	Drain-to-Source Inductance			18	,	nΗ	
C _{iss}	Input Capacitance		-	9.0	-	nF	V _{GS} =0V, V _{DS} =25V,
Coss	Output Capacitance			2.5	-	nF	f=1.0MHz
C _{rss}	Reverse Transfer Capacitance		_	0.7	-	nF	
	Linear Derating Factor		_	~	5	W/K	

Source-Drain Diode Ratings and Characteristics

	Parameter	Min.	Тур.	Max.	Units	Test Conditions
I _S	Continuous Source Current (Body Diode)		-	70	A	
I _{SM}	Pulsed Source Current (Body Diode)	-	_	245	Α	Н
V _{SD}	Diode Forward Voltage	-	-	2.0	٧	V _{GS} =0V, I _S = 70A, T _C =25°C
t _{rr}	Reverse Recovery Time	9160	320	640	ns	di/dt=400A/μs, T _J =150°C
Q _{rr}	Reverse Recovered Charge	6.6	13.0	26.0	μС	I _S =70A

Notes

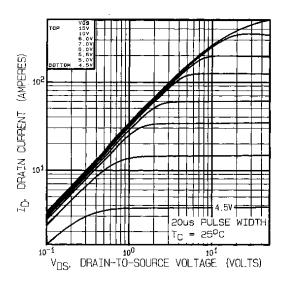


Fig 1. Typical Output Characteristics, $T_C=25^{\circ}C$

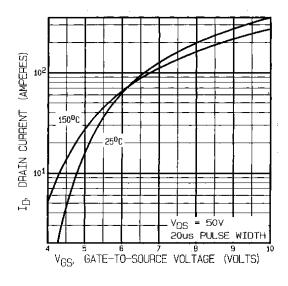


Fig 3. Typical Transfer Characteristics

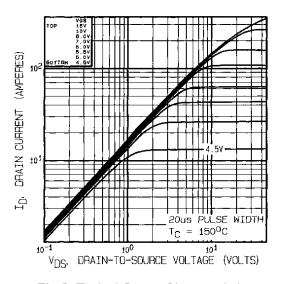


Fig 2. Typical Output Characteristics, $T_{\rm C}$ =150°C

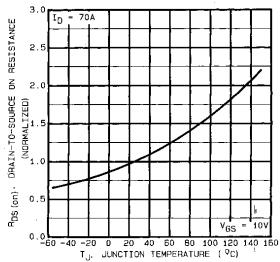


Fig 4. Normalized On-Resistance Vs. Temperature

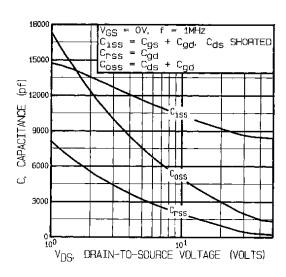


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

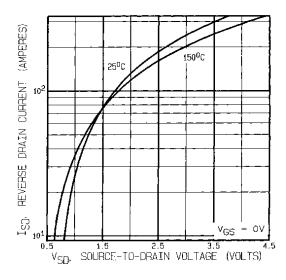


Fig 7. Typical Source-Drain Diode Forward Voltage

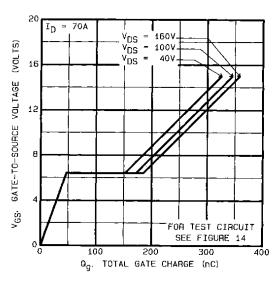


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

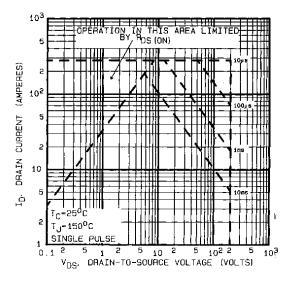


Fig 8. Maximum Safe Operating Area

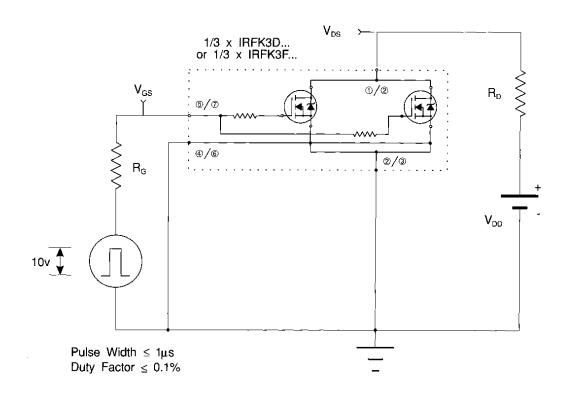


Fig 11a. Switching Time Test Circuit

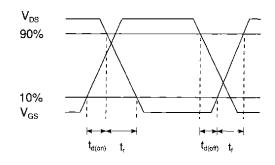


Fig 11b. Switching Time Waveforms

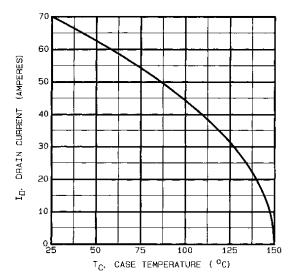


Fig 9. Maximum Drain Current Vs.
Case Temperature

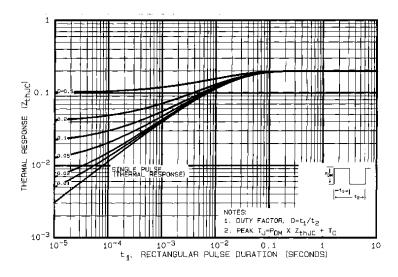
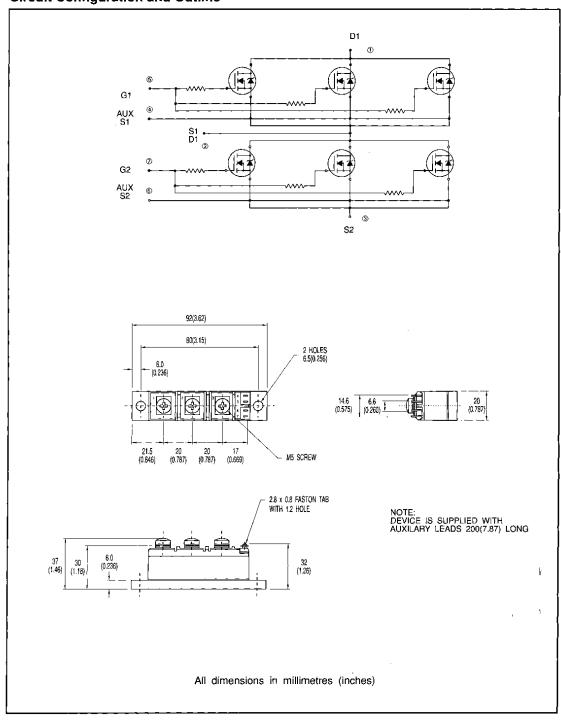


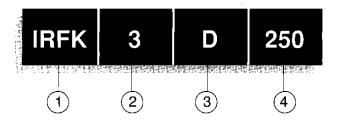
Fig 10. Maximum Effective Transient Thermal Impedance, Junction-to-Case

IRFK3D250,IRFK3F250

Circuit Configuration and Outline



Part Numbering



- HEX-pak Module.
- Number of arms of bridge.
- D Fast switching.
 - F Oscillation resistant for sensitive applications.
- 4. Voltage code:-054 - 60V

150 - 100V

250 - 200V

350 - 400V

450 - 500V

C50 - 600V

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MJW/1/92

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